Assembly & Protection Solutions

We have more than 50 years of experience developing and manufacturing structural bonding solutions and thermal management materials. Our extensive line of acrylic, epoxy, urethane and silicone solutions improve appearance, strength and durability, while offering design flexibility and cost savings. As a true partner, we offer up the right people, expertise and technology to get you where you need to go, wherever you may be.

Structural Adhesives



LORD® Adhesives

Compared to traditional fastening methods such as rivets, welds and tapes, our adhesives offer superior adhesion to a variety of substrates – eliminating costs associated with metal preparation and finishing operations to improve your manufacturing processes. We're proven in a variety of industries including transportation, off-highway and industrial.



Automotive Assembly Adhesives

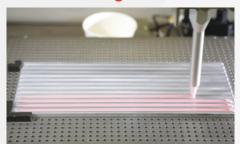
Build lightweight vehicles, lower emissions and replace mechanical fasteners with LORD® adhesives. Enable lower-cost assembly of automotive closure panels with Versilok® hem-flange adhesives. Our solutions are suitable for a wide variety of substrates and maintain their strength and durability.



Fusor® Repair Adhesives

We collaborate with our customers to provide OEM-approved products for the collision repair market. Our repair adhesives offer high standards of quality and performance that reduce cycle times for an increase in productivity. Fusor adhesives utilize various chemistries to meet your application needs.

Thermal Management Materials



Gap Fillers

Our CoolTherm® liquid-dispense, cure-in-place gap fillers couple high thermal conductivity and low viscosity. Applications include on-board chargers, battery packs and power electronics. They provide low stress and improve thermal resistance when compared to thermal pads.



Thermally Conductive Adhesives

We offer solutions that combine structural and thermal requirements for battery packs, cooling plates and charging systems. Our CoolTherm® adhesives provide high-bond strength and thermal conductivity.



Potting & Encapsulants

Potting and encapsulation products deliver a robust thermal interface resulting in reliable electronics. These CoolTherm® solutions improve performance by dissipating heat, protecting fragile components and reducing stress.

